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Siliup Semiconductor

SP010P80TQ

-100V P-Channel MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}TYP$	I_D
-100V	80mΩ@10V	-23A
	88mΩ@4.5V	

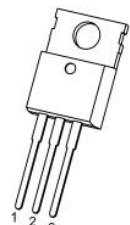
Feature

- Fast Switching
- Low Gate Charge and Rdson
- 100% Single Pulse avalanche energy Test

Applications

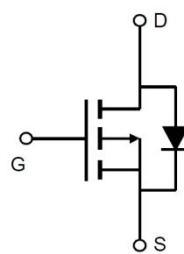
- Power switching application
- PWM Application
- DC-DC Converter

Package

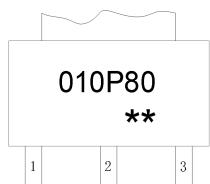


TO-220-3L-C(1:G 2:D 3:S)

Circuit diagram



Marking



010P80
** =Device Code
 =Week Code



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Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V _{DS}	-100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current(Tc=25°C)	I _D	-23	A
Pulsed Drain Current ²	I _{DM}	-92	A
Single Pulse Avalanche Energy ³	E _{AS}	137	mJ
Total Power Dissipation ⁴ (Tc=25°C)	P _D	96	W
Thermal Resistance Junction-Case ¹	R _{θJC}	1.3	°C/W
Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 150	°C

Electrical characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	VGS=0V , ID= -250uA	-100	---	---	V
Drain-Source Leakage Current	I _{DSS}	VDS= -24V , VGS=0V , TJ=25°C	---	---	1	uA
Gate-Source Leakage Current	I _{GSS}	VGS= ±20V , VDS=0V	---	---	±100	nA
Gate Threshold Voltage	V _{GS(th)}	VGS=VDS , ID = -250uA	-1.0	-1.7	-2.5	V
Static Drain-Source On-Resistance ²	R _{DS(ON)}	VGS= -10V , ID= -11A	---	80	95	mΩ
		VGS= -4.5V , ID=-8A	---	88	110	
Dynamic Characteristics						
Input Capacitance	C _{iss}	VDS= -25V , VGS=0V , f=1MHz	---	3029	---	pF
Output Capacitance	C _{oss}		---	129	---	
Reverse Transfer Capacitance	C _{rss}		---	76	---	
Switching Characteristics						
Total Gate Charge (4.5V)	Q _g	VDS= -50V , VGS= -10V , ID= -11A	---	44.5	---	nC
Gate-Source Charge	Q _{gs}		---	9.1	---	
Gate-Drain Charge	Q _{gd}		---	5.9	---	
Turn-On Delay Time	T _{d(on)}	VDD=-50V, ID=-16A, VGS=-10V, RGEN=9.1Ω	---	14	---	ns
Rise Time	T _r		---	71	---	
Turn-Off Delay Time	T _{d(off)}		---	34	---	
Fall Time	T _f		---	56	---	
Source-Drain Diode Characteristics						
Diode Forward Voltage ²	V _{SD}	VGS=0V , IS= -1A , TJ=25°C	---	---	1.2	V

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The EAS data shows Max. rating . The test condition is VDD=50V,VGS=10V,L=0.5mH,Rg=25Ω
4. The power dissipation is limited by 150°C junction temperature



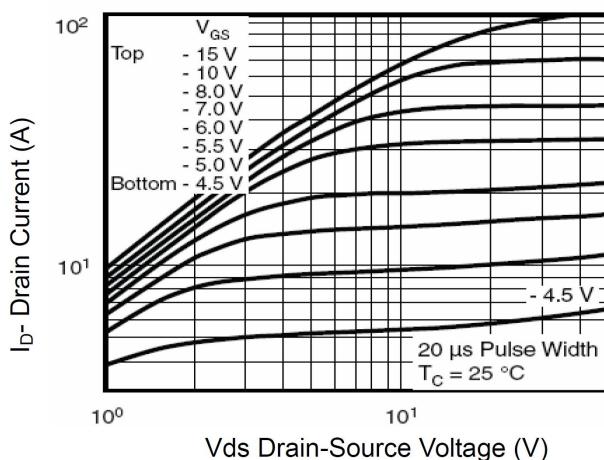
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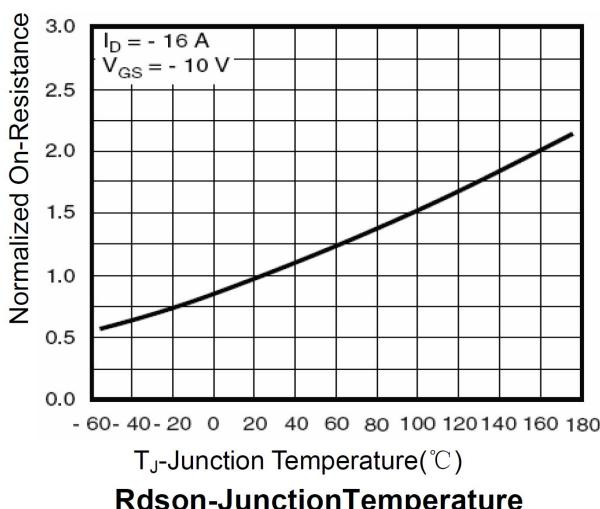
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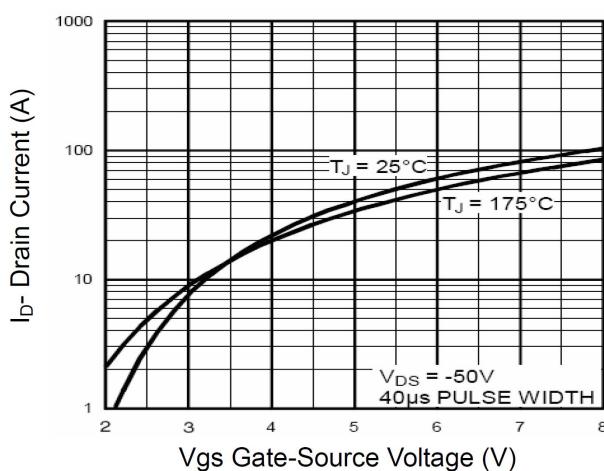
Typical Characteristics



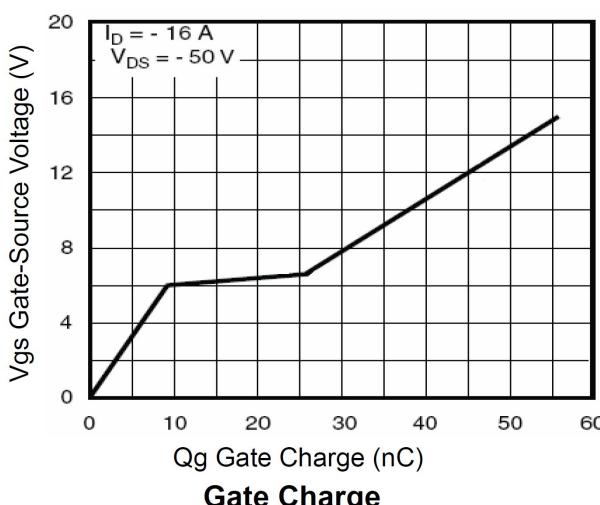
Output Characteristics



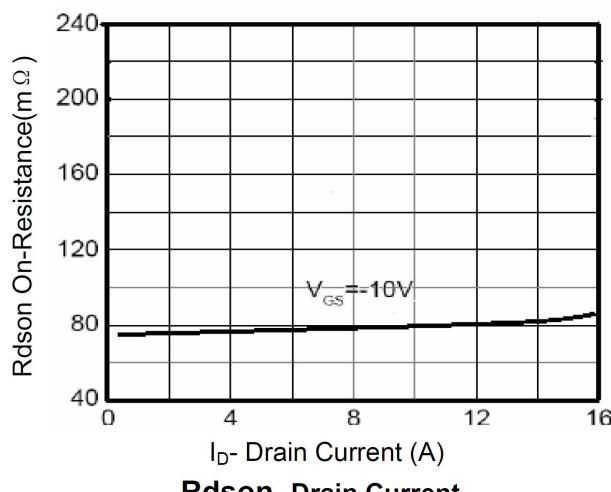
R_{dson}-JunctionTemperature



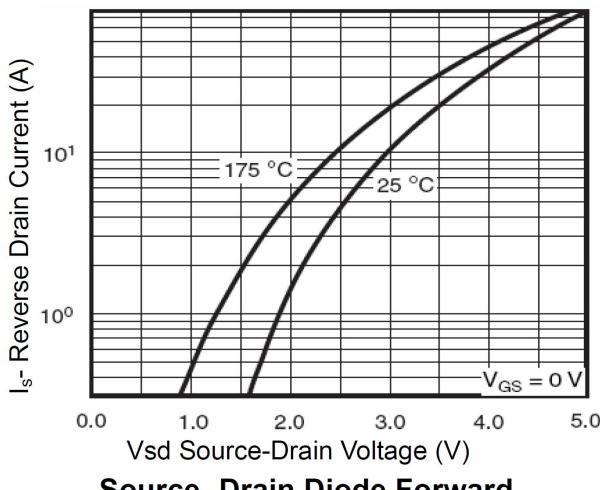
Transfer Characteristics



Gate Charge



R_{dson}- Drain Current



Source- Drain Diode Forward

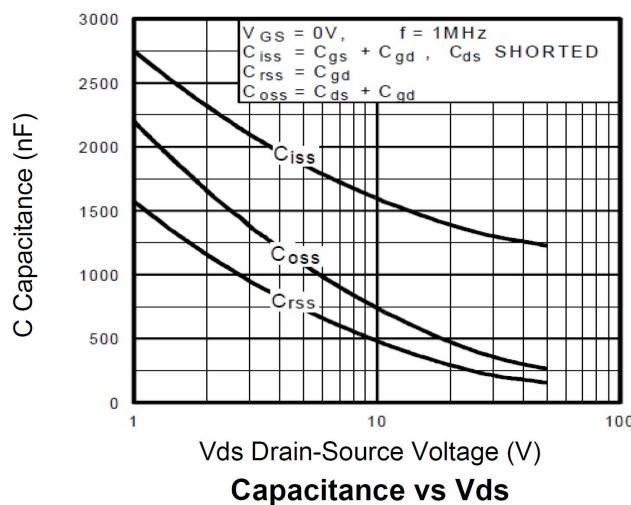


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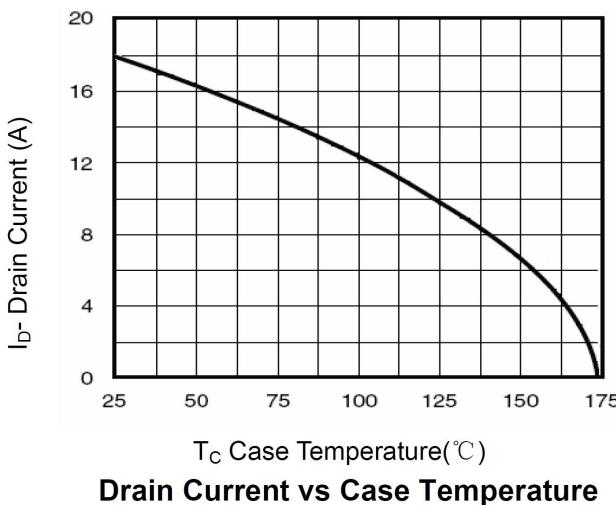
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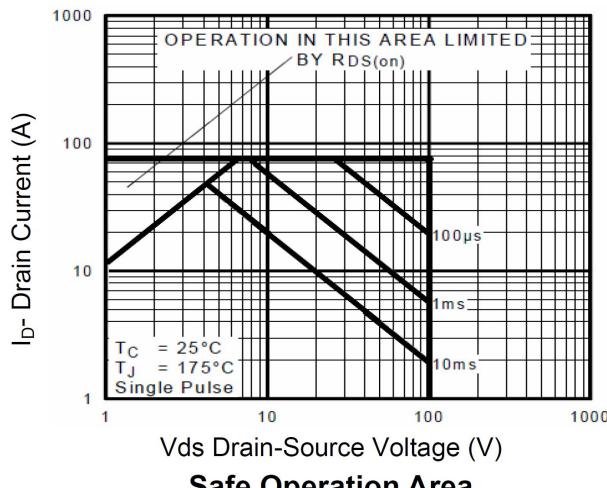
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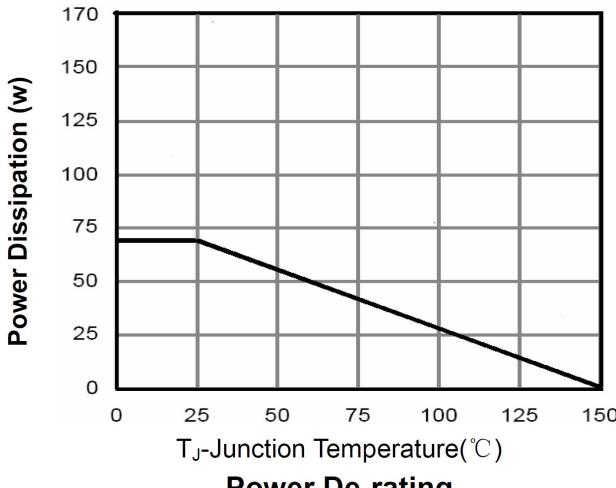
Capacitance vs Vds



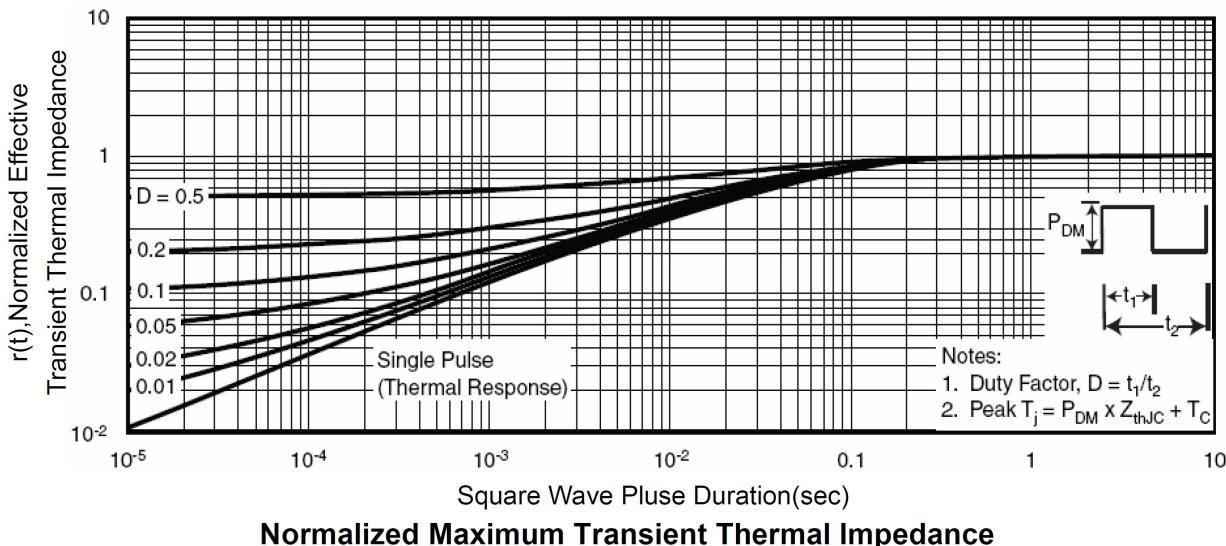
Drain Current vs Case Temperature



Safe Operation Area



Power De-rating



Normalized Maximum Transient Thermal Impedance



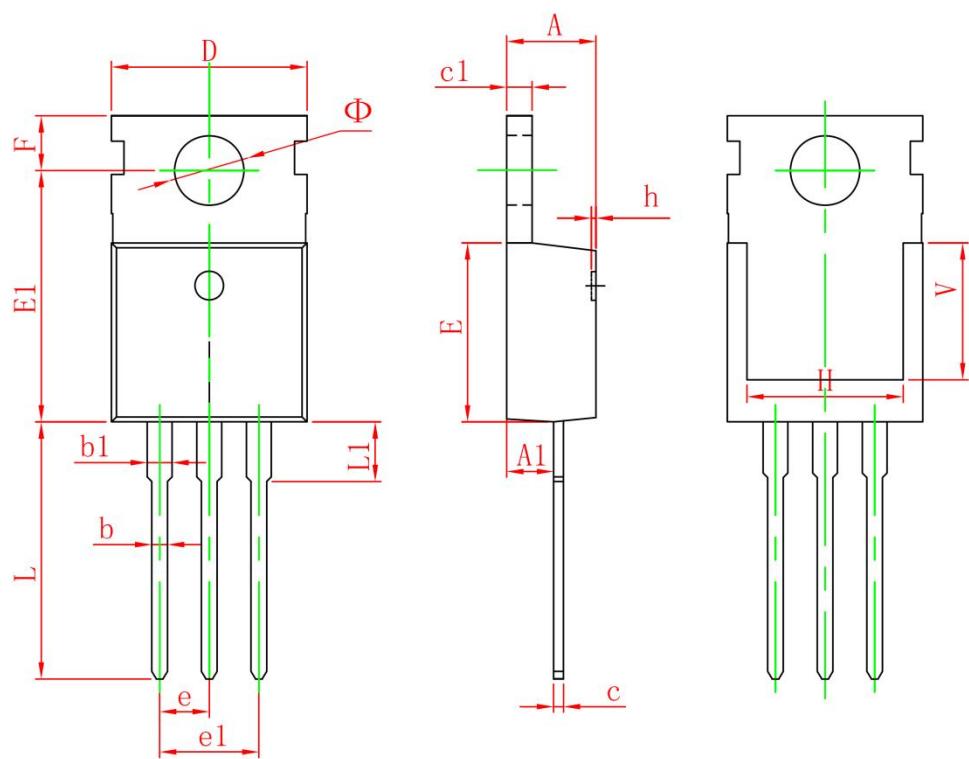
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TO-220-3L-C Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.950	9.750	0.352	0.384
E1	12.650	13.050	0.498	0.514
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF.		0.276 REF.	
Φ	3.400	3.800	0.134	0.150